

# DRAM

MT4C1M16C3  
MT4LC1M16C3

## FEATURES

- JEDEC- and industry-standard x16 timing, functions, pinouts and packages
- High-performance, low power CMOS silicon-gate process
- Single power supply ( $+3.3V \pm 0.3V$  or  $5V \pm 10\%$ )
- All inputs, outputs and clocks are TTL-compatible
- Refresh modes: RAS#-ONLY, CAS#-BEFORE-RAS# (CBR) and HIDDEN
- Optional Self Refresh (S) for low power data retention
- BYTE WRITE and BYTE READ access cycles
- 1,024-cycle refresh (10 row, 10 column addresses)
- 5V-tolerant inputs and I/Os on 3.3V devices

## OPTIONS

- Voltage
 

3.3V	LC
5V	C
- Packages
 

Plastic SOJ (400 mil)	DJ
Plastic TSOP (400 mil)	TG
- Timing
 

60ns access	-6
70ns access (3.3V only)	-7
- Refresh Rate
 

Standard 16ms period	None
Self Refresh and 128ms period	S
- Part Number Example: MT4LC1M16C3TG-6

*Note: The 1 Meg x 16 FPM DRAM base number differentiates the offerings in one place - MT4LC1M16C3. The third field distinguishes the low voltage offering: LC designates Vcc = 3.3V and C designates Vcc = 5V.*

## KEY TIMING PARAMETERS

SPEED	t <sub>RC</sub>	t <sub>RAC</sub>	t <sub>PC</sub>	t <sub>AA</sub>	t <sub>CAC</sub>	t <sub>RP</sub>
-6	110ns	60ns	35ns	30ns	15ns	40ns
-7	130ns	70ns	40ns	35ns	20ns	50ns

## GENERAL DESCRIPTION

The 1 Meg x 16 DRAM is a randomly accessed, solid-state memory containing 16,777,216 bits organized in a x16 configuration. The 1 Meg x 16 DRAM has both BYTE WRITE and WORD WRITE access cycles via two CAS# pins

## PIN ASSIGNMENT (Top View)

**42-Pin SOJ  
(DA-7)**

Vcc	1.	42	Vss	1.	50	Vss
DQ1	2	41	DQ16	2	49	DQ16
DQ2	3	40	DQ15	3	48	DQ15
DQ3	4	39	DQ14	4	47	DQ14
DQ4	5	38	DQ13	5	46	DQ13
Vcc	6	37	Vss	6	45	Vss
DQ5	7	36	DQ12	7	44	DQ12
DQ6	8	35	DQ11	8	43	DQ11
DQ7	9	34	DQ10	9	42	DQ10
DQ8	10	33	DQ9	10	41	DQ9
NC	11	32	NC	11	40	NC
NC	12	31	CASL#	12	36	NC
WE#	13	30	CASH#	13	35	CASL#
RAS#	14	29	OE#	14	34	CASH#
NC	15	28	A9	15	33	OE#
NC	16	27	A8	16	32	A9
A0	17	26	A7	17	31	A8
A1	18	25	A6	18	30	A7
A2	19	24	A5	19	29	A6
A3	20	23	A4	20	28	A5
Vcc	21	22	Vss	21	27	A4

**44/50-Pin TSOP  
(DB-6)**

Vcc	1.	42	Vcc	1.	50	Vss
DQ1	2	41	DQ16	2	49	DQ16
DQ2	3	40	DQ15	3	48	DQ15
DQ3	4	39	DQ14	4	47	DQ14
DQ4	5	38	DQ13	5	46	DQ13
Vcc	6	37	Vss	6	45	Vss
DQ5	7	36	DQ12	7	44	DQ12
DQ6	8	35	DQ11	8	43	DQ11
DQ7	9	34	DQ10	9	42	DQ10
DQ8	10	33	DQ9	10	41	DQ9
NC	11	32	NC	11	40	NC
NC	12	31	CASL#	12	36	NC
WE#	13	30	CASH#	13	35	CASL#
RAS#	14	29	OE#	14	34	CASH#
NC	15	28	A9	15	33	OE#
NC	16	27	A8	16	32	A9
A0	17	26	A7	17	31	A8
A1	18	25	A6	18	30	A7
A2	19	24	A5	19	29	A6
A3	20	23	A4	20	28	A5
Vcc	21	22	Vss	21	26	Vss

**Note:** The # symbol indicates signal is active LOW.

## 1 MEG x 16 FPM DRAM PART NUMBERS

PART NUMBER	VCC	PACKAGE	REFRESH
MT4LC1M16C3DJ	3.3V	SOJ	Standard
MT4LC1M16C3DJS	3.3V	SOJ	Self
MT4LC1M16C3TG	3.3V	TSOP	Standard
MT4LC1M16C3TGS	3.3V	TSOP	Self
MT4C1M16C3DJ	5V	SOJ	Standard
MT4C1M16C3DJS	5V	SOJ	Self
MT4C1M16C3TG	5V	TSOP	Standard
MT4C1M16C3TGS	5V	TSOP	Self

(CASL# and CASH#). These function in an identical manner to a single CAS# of other DRAMs in that either CASL# or CASH# will generate an internal CAS#.

The CAS# function and timing are determined by the first CAS# (CASL# or CASH#) to transition LOW and the last CAS# to transition back HIGH. Use of only one of the two results in a BYTE access cycle. CASL# transitioning LOW selects an access cycle for the lower byte (DQ1-DQ8) and CASH# transitioning LOW selects an access cycle for the upper byte (DQ9-DQ16).

## GENERAL DESCRIPTION (continued)

Each bit is uniquely addressed through the 20 address bits during READ or WRITE cycles. These are entered 10 bits (A0-A9) at a time. RAS# is used to latch the first 10 bits and CAS# the latter 10 bits. The CAS# function is determined by the first CAS# (CASL# or CASH#) to transition LOW and the last one to transition back HIGH. The CAS# function also determines whether the cycle will be a refresh cycle (RAS#-ONLY) or an active cycle (READ, WRITE or READ WRITE) once RAS# goes LOW.

The CASL# and CASH# inputs internally generate a CAS# signal functioning in an identical manner to the single CAS# input of other DRAMs. The key difference is each CAS# input (CASL# and CASH#) controls its corresponding DQ tristate logic (in conjunction with OE# and WE#). CASL# controls DQ1 through DQ8 and CASH# controls DQ9 through DQ16. The two CAS# controls give the 1 Meg x 16 DRAM BYTE WRITE cycle capabilities.

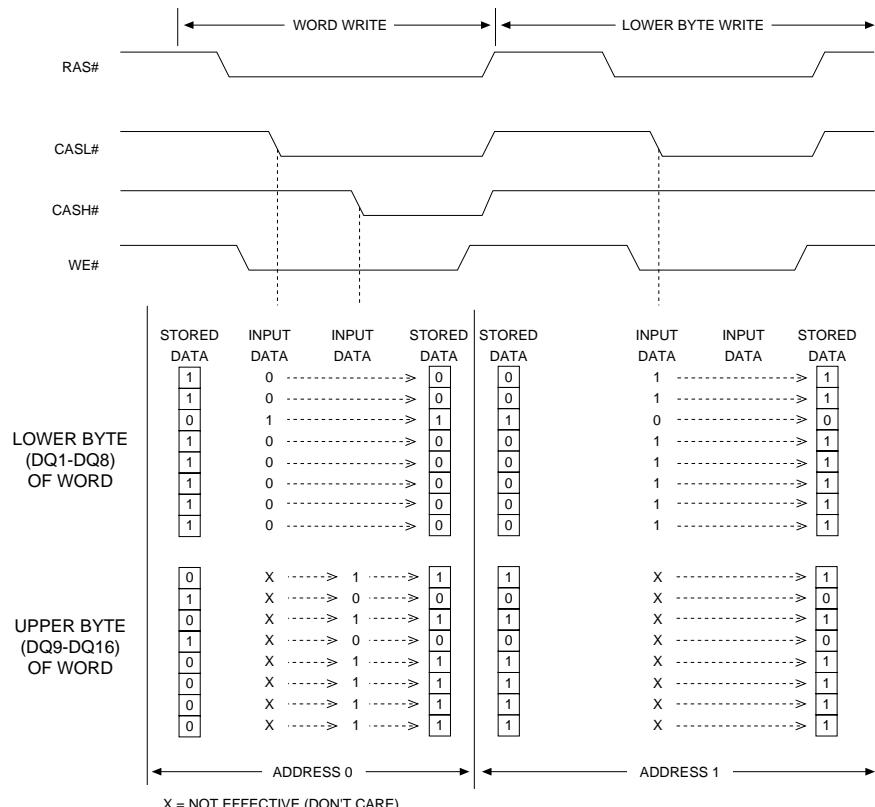
A logic HIGH on WE# dictates READ mode while a logic LOW on WE# dictates WRITE mode. During a WRITE cycle, data-in (D) is latched by the falling edge of WE# or CAS, whichever occurs last. Taking WE# LOW will initiate

a WRITE cycle, selecting DQ1 through DQ16. If WE# goes LOW prior to CAS# going LOW, the output pin(s) remain open (High-Z) until the next CAS# cycle. If WE# goes LOW after CAS# goes LOW and data reaches the output pins, data-out (Q) is activated and retains the selected cell data as long as CAS# and OE# remain LOW (regardless of WE# or RAS#). This late WE# pulse results in a READ WRITE cycle.

The 16 data inputs and 16 data outputs are routed through 16 pins using common I/O. Pin direction is controlled by OE# and WE#.

## FAST PAGE MODE

FAST PAGE MODE operations allow faster data operations (READ, WRITE or READ-MODIFY-WRITE) within a row-address-defined (A0-A9) page boundary. The FAST PAGE MODE cycle is always initiated with a row address strobed-in by RAS# followed by a column address strobed-in by CAS#. CAS# may be toggled-in by holding RAS# LOW and strobing-in different column addresses, thus executing faster memory cycles. Returning RAS# HIGH terminates the FAST PAGE MODE operation.



**Figure 1**  
**WORD AND BYTE WRITE EXAMPLE**

## FAST PAGE MODE (continued)

Returning RAS# and CAS# HIGH terminates a memory cycle and decreases chip current to a reduced standby level. The chip is also preconditioned for the next cycle during the RAS# HIGH time. Memory cell data is retained in its correct state by maintaining power and executing any RAS# cycle (READ, WRITE) or RAS# refresh cycle (RAS# ONLY, CBR, or HIDDEN) so that all 1,024 combinations of RAS# addresses (A0-A9) are executed at least every 16ms (128ms on the "S" version), regardless of sequence. The CBR Refresh cycle will also invoke the refresh counter and controller for row-address control.

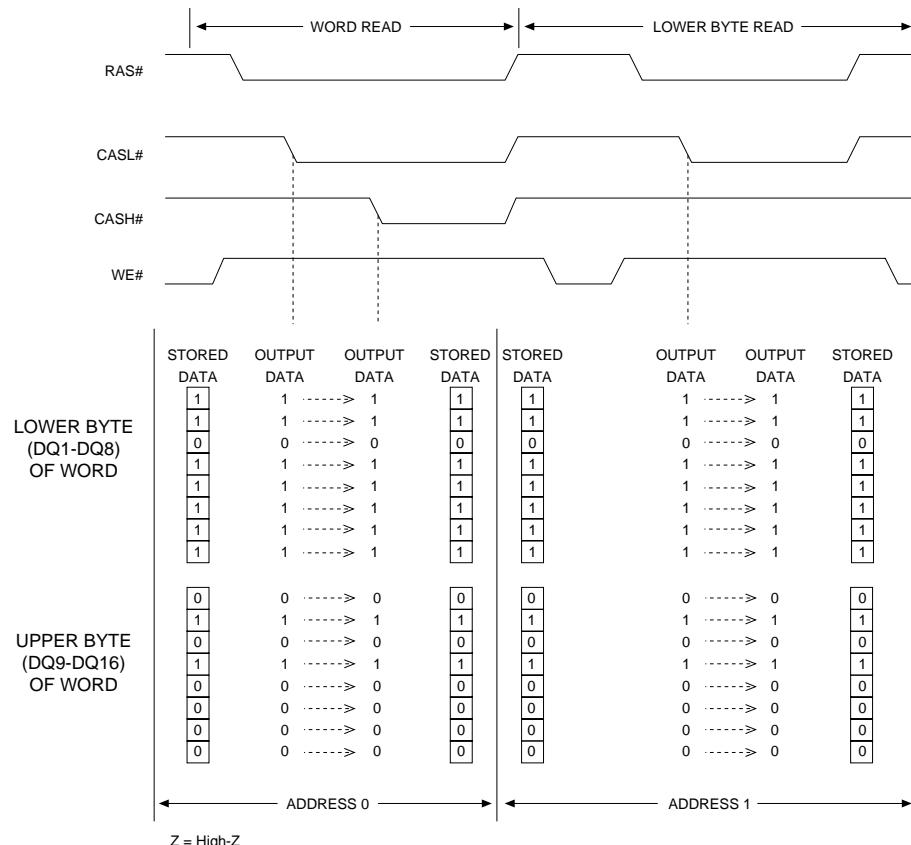
## BYTE ACCESS CYCLE

The BYTE WRITES and BYTE READs are determined by the use of CASL# and CASH#. Enabling CASL# will select a lower BYTE access (DQ1-DQ8). Enabling CASH# will

select an upper BYTE access (DQ9-DQ16). Enabling both CASL# and CASH# selects a WORD WRITE cycle.

The 1 Meg x 16 DRAM may be viewed as two 1 Meg x 8 DRAMs that have common input controls, with the exception of the CAS inputs. Figure 1 illustrates the BYTE WRITE and WORD WRITE cycles. Figure 2 illustrates BYTE READ and WORD READ cycles.

Additionally, both bytes must always be of the same mode of operation if both bytes are active. A CAS# precharge must be satisfied prior to changing modes of operation between the upper and lower bytes. For example, an EARLY WRITE on one byte and a LATE WRITE on the other byte are not allowed during the same cycle. However, an EARLY WRITE on one byte and, after a CAS# precharge has been satisfied, a LATE WRITE on the other byte are permissible.



**Figure 2**  
**WORD READ EXAMPLE**

## REFRESH

Preserve correct memory cell data by maintaining power and executing any RAS# cycle (READ, WRITE) or RAS# refresh cycle (RAS#-ONLY, CBR, or HIDDEN) so that all 1,024 combinations of RAS# addresses are executed within  $t_{REF}(\text{MAX})$ , regardless of sequence. The CBR and Extended and Self Refresh cycles will invoke the internal refresh counter for automatic RAS# addressing.

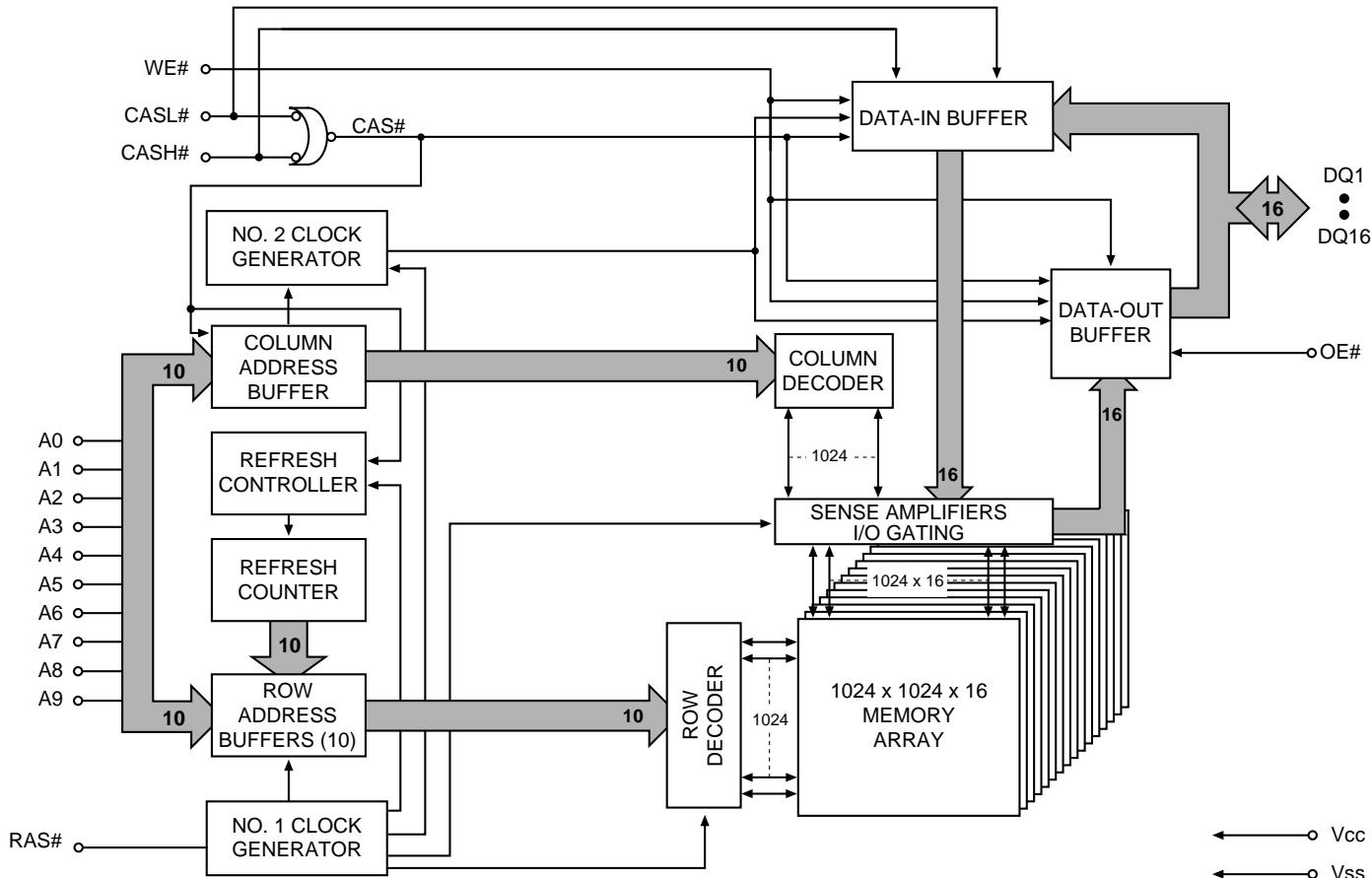
The optional Self Refresh mode is available on the "S" version. The "S" option allows the user a dynamic refresh, data retention mode at the extended refresh period of 128ms, i.e. 125 $\mu$ s per row when using distributed CBR refreshes. The "S" option also allows the user the choice of a fully static low-power data retention mode. The optional Self Refresh feature is initiated by performing a CBR Refresh cycle and holding RAS# LOW for the specified  $t_{RASS}$ .

The Self Refresh mode is terminated by driving RAS# HIGH for a minimum time of  $t_{RPS}$ . This delay allows for the completion of any internal refresh cycles that may be in process at the time of the RAS# LOW-to-HIGH transition. If the DRAM controller uses a distributed refresh sequence, a burst refresh is not required upon exiting Self Refresh. However, if the DRAM controller utilizes RAS#-ONLY or burst refresh sequence, all 1,024 rows must be refreshed within the average internal refresh rate prior to the resumption of normal operation.

## STANDBY

Returning RAS# and CAS# HIGH terminates a memory cycle and decreases chip current to a reduced standby level. The chip is preconditioned for the next cycle during the RAS# HIGH time.

## FUNCTIONAL BLOCK DIAGRAM



## TRUTH TABLE

FUNCTION	RAS#	CASL#	CASH#	WE#	OE#	ADDRESSES		DQs	NOTES
						t <sub>R</sub>	t <sub>C</sub>		
Standby	H	H→X	H→X	X	X	X	X	High-Z	
READ: WORD	L	L	L	H	L	ROW	COL	Data-Out	
READ: LOWER BYTE	L	L	H	H	L	ROW	COL	Lower Byte, Data-Out Upper Byte, Data-Out	
READ: UPPER BYTE	L	H	L	H	L	ROW	COL	Lower Byte, Data-Out Upper Byte, Data-Out	
WRITE: WORD (EARLY WRITE)	L	L	L	L	X	ROW	COL	Data-In	
WRITE: LOWER BYTE (EARLY)	L	L	H	L	X	ROW	COL	Lower Byte, Data-In Upper Byte, High-Z	
WRITE: UPPER BYTE (EARLY)	L	H	L	L	X	ROW	COL	Lower Byte, High-Z Upper Byte, Data-In	
READ WRITE	L	L	L	H→L	L→H	ROW	COL	Data-Out, Data-In	1
PAGE-MODE	1st Cycle	L	H→L	H→L	H	L	ROW	COL	Data-Out
READ	2nd Cycle	L	H→L	H→L	H	L	n/a	COL	Data-Out
PAGE-MODE	1st Cycle	L	H→L	H→L	L	X	ROW	COL	Data-In
WRITE	2nd Cycle	L	H→L	H→L	L	X	n/a	COL	Data-In
PAGE-MODE	1st Cycle	L	H→L	H→L	H→L	L→H	ROW	COL	Data-Out, Data-In
READ-WRITE	2nd Cycle	L	H→L	H→L	H→L	L→H	n/a	COL	Data-Out, Data-In
HIDDEN	READ	L→H→L	L	L	H	L	ROW	COL	Data-Out
REFRESH	WRITE	L→H→L	L	L	L	X	ROW	COL	Data-In
RAS#-ONLY REFRESH		L	H	H	X	X	ROW	n/a	High-Z
CBR REFRESH		H→L	L	L	H	X	X	High-Z	3
SELF REFRESH		H→L	L	L	H	X	X	High-Z	3

**NOTE:** 1. These WRITE cycles may also be BYTE WRITE cycles (either CASL# or CASH# active).

2. EARLY WRITE only.

3. Only one CAS# must be active (CASL# or CASH#).

## ABSOLUTE MAXIMUM RATINGS\*

Voltage on Vcc pin Relative to Vss:

3.3V .....	-1V to +4.6V
5V .....	-1V to +7V

Voltage on NC, Inputs or I/O pins Relative to Vss:

3.3V .....	-1V to +5.5V
5V .....	-1V to +7V

Operating Temperature,  $T_A$  (ambient) ..... 0°C to +70°C

Storage Temperature (plastic) ..... -55°C to +150°C

Power Dissipation ..... 1W

Short Circuit Output Current ..... 50mA

\*Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## DC ELECTRICAL CHARACTERISTICS AND OPERATING CONDITIONS

(Notes: 1, 2, 3)

PARAMETER/CONDITION	SYMBOL	3.3V		5V		UNITS	NOTES
		MIN	MAX	MIN	MAX		
Supply Voltage	V <sub>CC</sub>	3.0	3.6	4.5	5.5	V	
Input High Voltage: Valid Logic 1; all inputs, I/Os and any NC	V <sub>IH</sub>	2.0	5.5	2.4	V <sub>CC</sub> +1	V	
Input Low Voltage: Valid Logic 0; all inputs, I/Os and any NC	V <sub>IL</sub>	-1.0	0.8	-0.5	0.8	V	
Input Leakage Current: Any input at V <sub>IN</sub> (0V ≤ V <sub>IN</sub> ≤ V <sub>IH</sub> <sub>MAX</sub> ); all other pins not under test = 0V	I <sub>I</sub>	-2	2	-2	2	µA	
Output High Voltage: I <sub>OUT</sub> = -2mA (3.3V), -5mA (5.0V)	V <sub>OH</sub>	2.4	-	2.4	-	V	
Output Low Voltage: I <sub>OUT</sub> = 2mA (3.3V), 4.2mA (5.0V)	V <sub>OL</sub>	-	0.4	-	0.4	V	
Output Leakage Current: Any output at V <sub>OUT</sub> (0V ≤ V <sub>OUT</sub> ≤ 5.5V); DQ is disabled and in High-Z state	I <sub>OZ</sub>	-5	5	-5	5	µA	

## I<sub>CC</sub> OPERATING CONDITIONS AND MAXIMUM LIMITS

(Notes: 1, 2, 3) ( $V_{CC_{MIN}} \leq V_{CC} \leq V_{CC_{MAX}}$ )

PARAMETER/CONDITION	SYM	SPEED	3.3V	5V	UNITS	NOTES
STANDBY CURRENT: TTL (RAS# = CAS# = V <sub>IH</sub> )	I <sub>CC1</sub>	ALL	1	2	mA	
STANDBY CURRENT: CMOS (non-S version only) (RAS# = CAS# = other inputs = V <sub>CC</sub> -0.2V)	I <sub>CC2</sub>	ALL	500	500	μA	22
STANDBY CURRENT: CMOS (S version only) (RAS# = CAS# = other inputs = V <sub>CC</sub> -0.2V)	I <sub>CC2</sub>	ALL	150	150	μA	22
OPERATING CURRENT: Random READ/WRITE Average power supply current (RAS#, CAS#, address cycling: t <sub>RC</sub> = t <sub>RC</sub> [MIN])	I <sub>CC3</sub>	-6	170	180	mA	3, 23
		-7	160	—		
OPERATING CURRENT: FAST PAGE MODE Average power supply current (RAS# = V <sub>IL</sub> , CAS#, address cycling: t <sub>PC</sub> = t <sub>PC</sub> [MIN])	I <sub>CC4</sub>	-6	90	110	mA	3, 23
		-7	80	—		
REFRESH CURRENT: RAS#-ONLY Average power supply current (RAS# cycling, CAS# = V <sub>IH</sub> ; t <sub>RC</sub> = t <sub>RC</sub> [MIN])	I <sub>CC5</sub>	-6	170	180	mA	3
		-7	160	—		
REFRESH CURRENT: CBR Average power supply current (RAS#, CAS#, address cycling: t <sub>RC</sub> = t <sub>RC</sub> [MIN])	I <sub>CC6</sub>	-6	170	180	mA	3, 4
		-7	160	—		
REFRESH CURRENT: Extended (S version only) Average power supply current: CAS# = 0.2V or CBR cycling; RAS# = t <sub>RAS</sub> (MIN); WE# = V <sub>CC</sub> -0.2V; A0-A11, OE# and DIN = V <sub>CC</sub> -0.2V or 0.2V (DIN may be left open)	I <sub>CC7</sub>	ALL	300	300	μA	3, 4
REFRESH CURRENT: Self (S version only) Average power supply current: CBR with RAS# ≥ t <sub>RASS</sub> (MIN) and CAS# held LOW; WE# = V <sub>CC</sub> -0.2V; A0-A11, OE# and DIN = V <sub>CC</sub> -0.2V or 0.2V (DIN may be left open)	I <sub>CC8</sub>	ALL	300	300	μA	3, 4

## CAPACITANCE

PARAMETER	SYMBOL	MAX	UNITS	NOTES
Input Capacitance: Addresses	$C_{I1}$	5	pF	2
Input Capacitance: RAS#, CASL#, CASH#, WE#, OE#	$C_{I2}$	7	pF	2
Input/Output Capacitance: DQ	$C_{IO}$	7	pF	2

## AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 10, 11, 12) ( $V_{CC_{MIN}} \leq V_{CC} \leq V_{CC_{MAX}}$ )

AC CHARACTERISTICS	SYM	-6		-7*		UNITS	NOTES
		MIN	MAX	MIN	MAX		
Access time from column address	$t_{AA}$		30		35	ns	
Column-address hold time (referenced to RAS#)	$t_{AR}$	45		55		ns	
Column-address setup time	$t_{ASC}$	0		0		ns	27
Row-address setup time	$t_{ASR}$	0		0		ns	
Column-address to WE# delay time	$t_{AWD}$	55		60		ns	18
Access time from CAS	$t_{CAC}$		15		20	ns	29
Column-address hold time	$t_{CAH}$	10		12		ns	27
CAS# pulse width	$t_{CAS}$	15	10,000	20	10,000	ns	35
CAS# LOW to "don't care" during Self Refresh	$t_{CHD}$	15		15		ns	
CAS# hold time (CBR Refresh)	$t_{CHR}$	10		15		ns	4, 28
Last CAS# going LOW to first CAS# to return HIGH	$t_{CLCH}$	10		10		ns	31
CAS# to output in Low-Z	$t_{CLZ}$	3		3		ns	26, 29
CAS# precharge time	$t_{CP}$	10		10		ns	32
Access time from CAS# precharge	$t_{CPA}$		35		40	ns	28
CAS# to RAS# precharge time	$t_{CRP}$	5		5		ns	28
CAS# hold time	$t_{CSH}$	60		70		ns	28
CAS# setup time (CBR Refresh)	$t_{CSR}$	5		5		ns	4, 27
CAS# to WE# delay time	$t_{CWD}$	40		45		ns	18, 27
Write command to CAS# lead time	$t_{CWL}$	15		20		ns	23, 30
Data-in hold time	$t_{DH}$	10		12		ns	19, 29
Data-in setup time	$t_{DS}$	0		0		ns	19, 29
Output disable	$t_{OD}$	3	15	3	20	ns	25, 26, 37
Output enable	$t_{OE}$		15		20	ns	30
OE# hold time from WE# during READ-MODIFY-WRITE cycle	$t_{OEH}$	15		20		ns	25
Output buffer turn-off delay	$t_{OFF}$	3	15	3	20	ns	17, 26, 29
OE# setup prior to RAS# during HIDDEN Refresh cycle	$t_{ORD}$	0		0		ns	
FAST-PAGE-MODE READ or WRITE cycle time	$t_{PC}$	35		40		ns	31
FAST-PAGE-MODE READ-WRITE cycle time	$t_{PRWC}$	85		95		ns	31

\*3.3V only

## AC ELECTRICAL CHARACTERISTICS

(Notes: 5, 6, 7, 8, 9, 10, 11, 12) ( $V_{CC_{MIN}} \leq V_{CC} \leq V_{CC_{MAX}}$ )

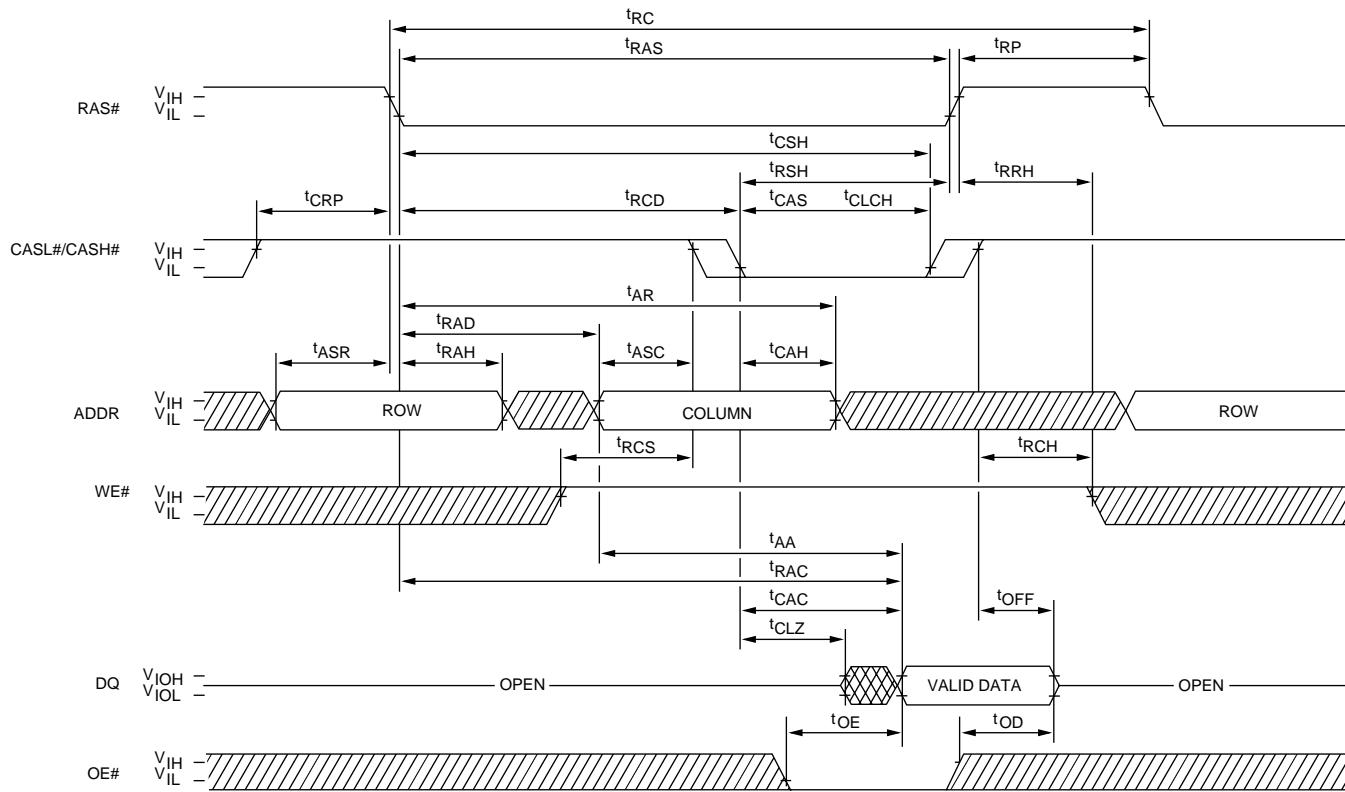
AC CHARACTERISTICS		-6		-7*			
PARAMETER	SYM	MIN	MAX	MIN	MAX	UNITS	NOTES
Access time from RAS#	t <sub>RAC</sub>		60		70	ns	
RAS# to column-address delay time	t <sub>RAD</sub>	15		15		ns	15
Row-address hold time	t <sub>RAH</sub>	10		10		ns	
RAS# pulse width	t <sub>RAS</sub>	60	10,000	70	10,000	ns	
RAS# pulse width (FAST PAGE MODE)	t <sub>RASP</sub>	60	125,000	70	125,000	ns	
RAS# pulse width (Self Refresh)	t <sub>RASS</sub>	100		100		μs	
Random READ or WRITE cycle time	t <sub>RC</sub>	110		130		ns	
RAS# to CAS# delay time	t <sub>RCD</sub>	20		20		ns	14, 27
Read command hold time (referenced to CAS)	t <sub>RCH</sub>	0		0		ns	16, 28
Read command setup time	t <sub>RCS</sub>	0		0		ns	27
Refresh period (1,024 cycles)	t <sub>REF</sub>		16		16	ms	
Refresh period (1,024 cycles) S version	t <sub>REF</sub>		128		128	ms	
RAS# precharge time	t <sub>RP</sub>	40		50		ns	
RAS# to CAS# precharge time	t <sub>RPC</sub>	0		0		ns	
RAS# precharge time (Self Refresh)	t <sub>RPS</sub>	110		130		ns	
Read command hold time (referenced to RAS#)	t <sub>RRH</sub>	0		0		ns	16
RAS# hold time	t <sub>RSH</sub>	15		20		ns	36
READ WRITE cycle time	t <sub>RWC</sub>	155		180		ns	
RAS# to WE# delay time	t <sub>RWD</sub>	85		95		ns	18
Write command to RAS# lead time	t <sub>RWL</sub>	15		20		ns	
Transition time (rise or fall)	t <sub>T</sub>	2	50	2	50	ns	
Write command hold time	t <sub>WCH</sub>	10		12		ns	36
Write command hold time (referenced to RAS#)	t <sub>WCR</sub>	45		55		ns	
WE# command setup time	t <sub>WCS</sub>	0		0		ns	18, 27
Write command pulse width	t <sub>WP</sub>	10		15		ns	
WE# hold time (CBR Refresh)	t <sub>WRH</sub>	10		10		ns	
WE# setup time (CBR Refresh)	t <sub>WRP</sub>	10		10		ns	

\*3.3V only

## NOTES

1. All voltages referenced to Vss.
2. This parameter is sampled. VCC = +3V; f = 1 MHz.
3. ICC is dependent on output loading. Specified values are obtained with minimum cycle time and the output open.
4. Enables on-chip refresh and address counters.
5. The minimum specifications are used only to indicate cycle time at which proper operation over the full temperature range ( $0^{\circ}\text{C} \leq T_A \leq 70^{\circ}\text{C}$ ) is ensured.
6. An initial pause of 100 $\mu\text{s}$  is required after power-up, followed by eight RAS# refresh cycles (RAS#-ONLY or CBR), before proper device operation is ensured. The eight RAS# cycle wake-ups should be repeated any time the tREF refresh requirement is exceeded.
7. AC characteristics assume tT = 5ns.
8. VIH (MIN) and Vil (MAX) are reference levels for measuring timing of input signals. Transition times are measured between VIH and Vil (or between Vil and VIH).
9. In addition to meeting the transition rate specification, all input signals must transit between VIH and Vil (or between Vil and VIH) in a monotonic manner.
10. If CAS# = VIH, data output is High-Z.
11. If CAS# = Vil, data output may contain data from the last valid READ cycle.
12. Measured with a load equivalent to two TTL gates, 100pF and VOL = 0.8V and VOH = 2V.
13. If CAS# is LOW at the falling edge of RAS#, Q will be maintained from the previous cycle. To initiate a new cycle and clear the Q buffer, CAS# must be pulsed HIGH for tCP.
14. The tRCD (MAX) limit is no longer specified. tRCD (MAX) was specified as a reference point only. If tRCD was greater than the specified tRCD (MAX) limit, then access time was controlled exclusively by tCAC (tRAC [MIN] no longer applied). With or without the tRCD limit, tAA and tCAC must always be met.
15. The tRAD (MAX) limit is no longer specified. tRAD (MAX) was specified as a reference point only. If tRAD was greater than the specified tRAD (MAX) limit, then access time was controlled exclusively by tAA (tRAC and tCAC no longer applied). With or without the tRAD (MAX) limit, tAA, tRAC and tCAC must always be met.
16. Either tRCH or tRRH must be satisfied for a READ cycle.
17. tOFF (MAX) defines the time at which the output achieves the open circuit condition; it is not a reference to VOL or VOL.
18. tWCS, tRWD, tAWD and tCWD are restrictive operating parameters in LATE WRITE and READ-MODIFY-WRITE cycles only. If tWCS  $\geq$  tWCS (MIN), the cycle is an EARLY WRITE cycle and the data output will remain an open circuit throughout the entire cycle. If tRWD  $\geq$  tRWD (MIN), tAWD  $\geq$  tAWD (MIN) and tCWD  $\geq$  tCWD (MIN), the cycle is a READ WRITE and the data output will contain data read from the selected cell. If neither of the above conditions is met, the state of Q (at access time and until CAS# or OE# goes back to VIH) is indeterminate. OE# held HIGH and WE# taken LOW after CAS# goes LOW result in a LATE WRITE (OE#-controlled) cycle.
19. These parameters are referenced to CAS# leading edge in EARLY WRITE cycles and WE# leading edge in LATE WRITE or READ-MODIFY-WRITE cycles.
20. During a READ cycle, if OE# is LOW then taken HIGH before CAS# goes HIGH, Q goes open. If OE# is tied permanently LOW, LATE WRITE and READ-MODIFY-WRITE operations are not permissible and should not be attempted.
21. A HIDDEN REFRESH may also be performed after a WRITE cycle. In this case, WE# = LOW and OE# = HIGH.
22. All other inputs at 0.2V or VCC -0.2V.
23. Column address changed once each cycle.
24. LATE WRITE and READ-MODIFY-WRITE cycles must have both tOD and tOEH met (OE# HIGH during WRITE cycle) in order to ensure that the output buffers will be open during the WRITE cycle. The DQs will provide the previously read data if CAS# remains LOW and OE# is taken back LOW after tOEH is met. If CAS# goes HIGH prior to OE# going back LOW, the DQs will remain open.
25. The DQs open during READ cycles once tOD or tOFF occur.
26. The 3ns minimum is a parameter guaranteed by design.
27. The first CASx edge to transition LOW.
28. The last CASx edge to transition HIGH.
29. Output parameter (DQx) is referenced to corresponding CAS# input; DQ1-DQ8 by CASL# and DQ9-DQ16 by CASH#.
30. Last falling CASx edge to first rising CASx edge.
31. Last rising CASx edge to next cycle's last rising CASx edge.
32. Last rising CASx edge to first falling CASx edge.
33. First DQs controlled by the first CASx to go LOW.
34. Last DQs controlled by the last CASx to go HIGH.
35. Each CASx must meet minimum pulse width.
36. Last CASx to go LOW.
37. All DQs controlled, regardless CASL# and CASH#.

### READ CYCLE



DON'T CARE

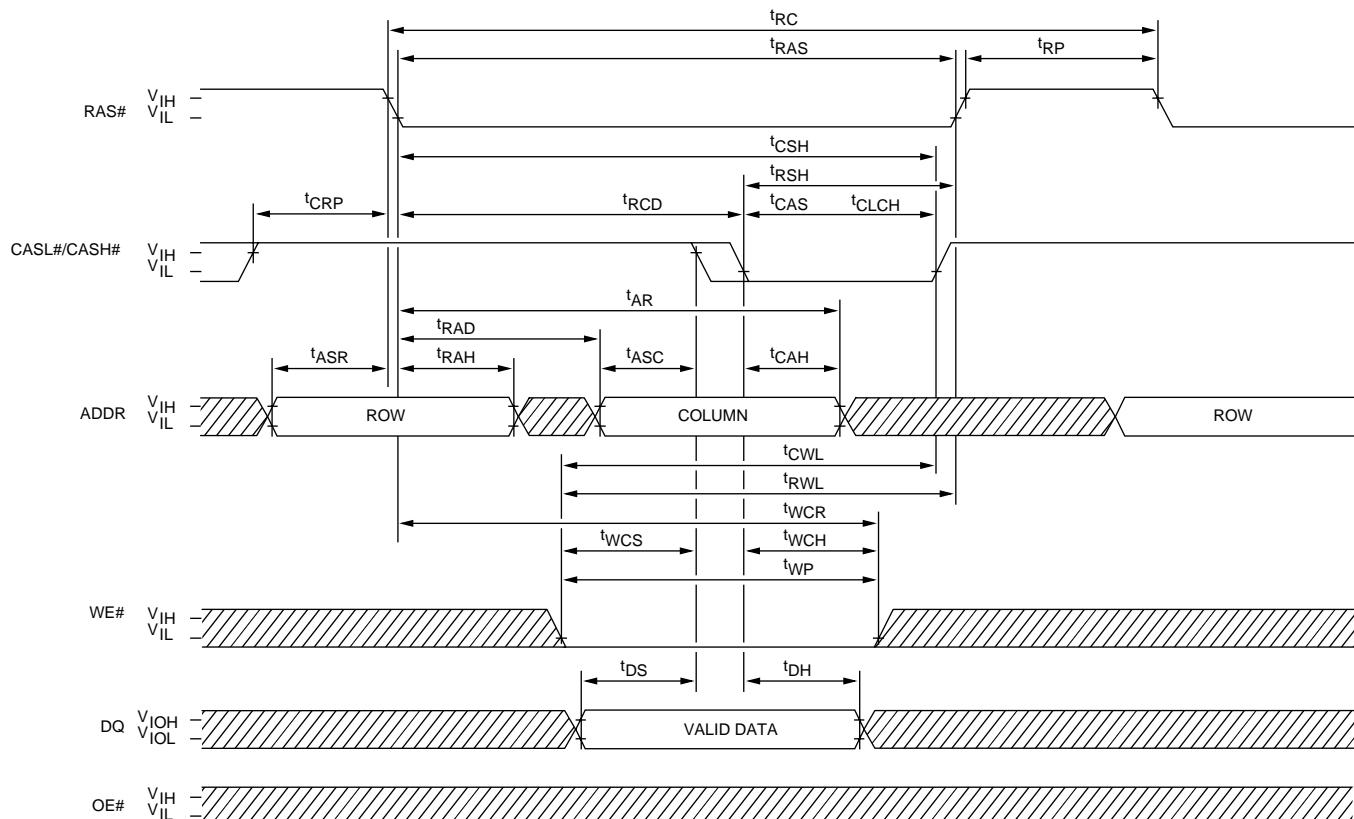
UNDEFINED

### TIMING PARAMETERS

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>AA</sub>		30		35	ns
t <sub>AR</sub>	45		55		ns
t <sub>ASC</sub>	0		0		ns
t <sub>ASR</sub>	0		0		ns
t <sub>CAC</sub>		15		20	ns
t <sub>CAH</sub>	10		12		ns
t <sub>CAS</sub>	15	10,000	20	10,000	ns
t <sub>CLCH</sub>	10		10		ns
t <sub>CLZ</sub>	3		3		ns
t <sub>CRP</sub>	5		5		ns
t <sub>CSH</sub>	60		70		ns
t <sub>OD</sub>	3	15	3	20	ns
t <sub>OE</sub>		15		20	ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>OFF</sub>	3	15	3	20	ns
t <sub>RAC</sub>			60		ns
t <sub>RAD</sub>	15			15	ns
t <sub>RAH</sub>	10			10	ns
t <sub>RAS</sub>	60	10,000	70	10,000	ns
t <sub>RC</sub>	110		130		ns
t <sub>RCD</sub>	20			20	ns
t <sub>RCH</sub>	0		0		ns
t <sub>RCS</sub>	0		0		ns
t <sub>RP</sub>	40		50		ns
t <sub>RRH</sub>	0		0		ns
t <sub>RSH</sub>	15		20		ns

### EARLY WRITE CYCLE



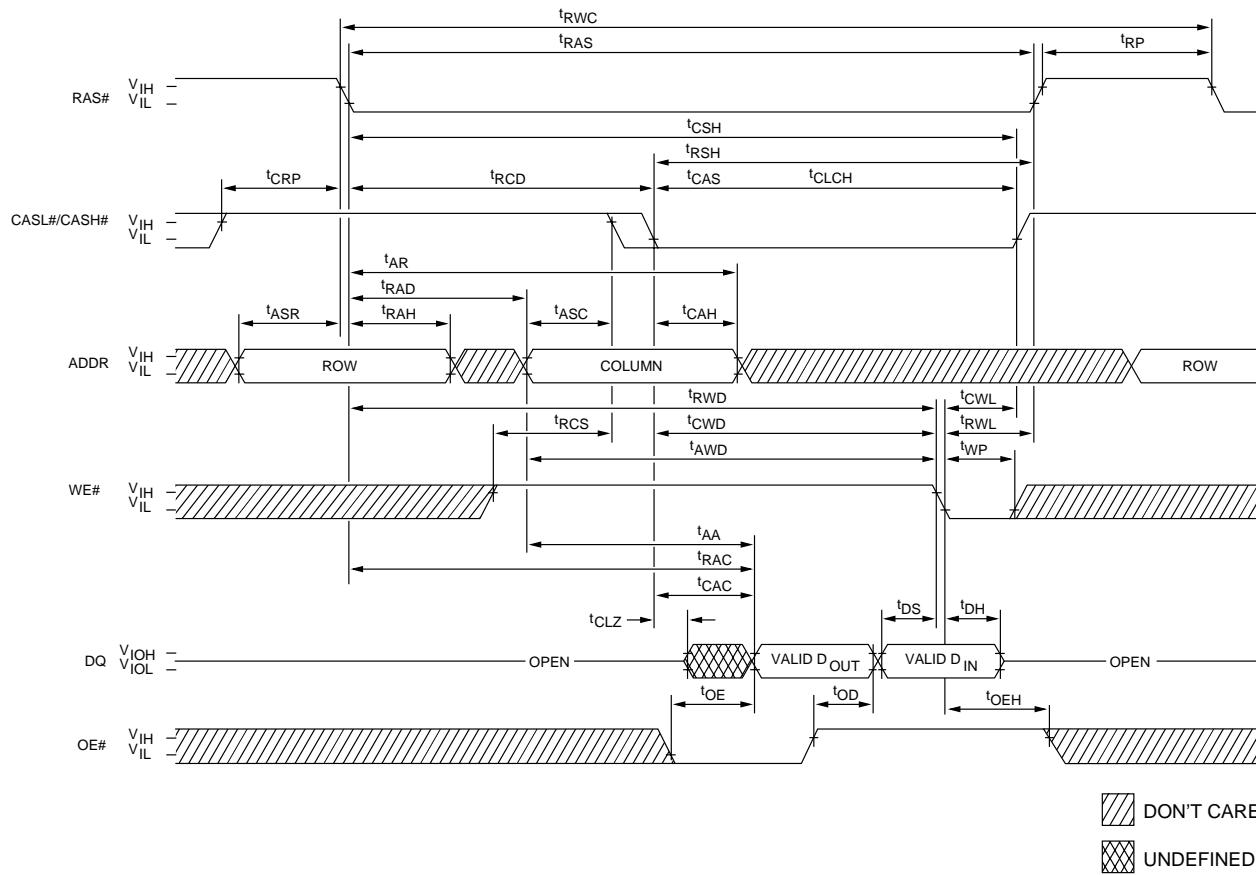
DON'T CARE  
 UNDEFINED

### TIMING PARAMETERS

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
$t_{AR}$	45		55		ns
$t_{ASC}$	0		0		ns
$t_{ASR}$	0		0		ns
$t_{CAH}$	10		12		ns
$t_{CAS}$	15	10,000	20	10,000	ns
$t_{CLCH}$	10		10		ns
$t_{CRP}$	5		5		ns
$t_{CSH}$	60		70		ns
$t_{CWL}$	15		20		ns
$t_{DH}$	10		12		ns
$t_{DS}$	0		0		ns
$t_{RAD}$	15		15		ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
$t_{RAH}$	10		10		ns
$t_{RAS}$	60	10,000	70	10,000	ns
$t_{RC}$	110		130		ns
$t_{RCD}$	20		20		ns
$t_{RP}$	40		50		ns
$t_{RSH}$	15		20		ns
$t_{RWL}$	15		20		ns
$t_{WCH}$	10		12		ns
$t_{WCR}$	45		55		ns
$t_{WCS}$	0		0		ns
$t_{WP}$	10		15		ns

**READ WRITE CYCLE**  
(LATE WRITE and READ-MODIFY-WRITE cycles)

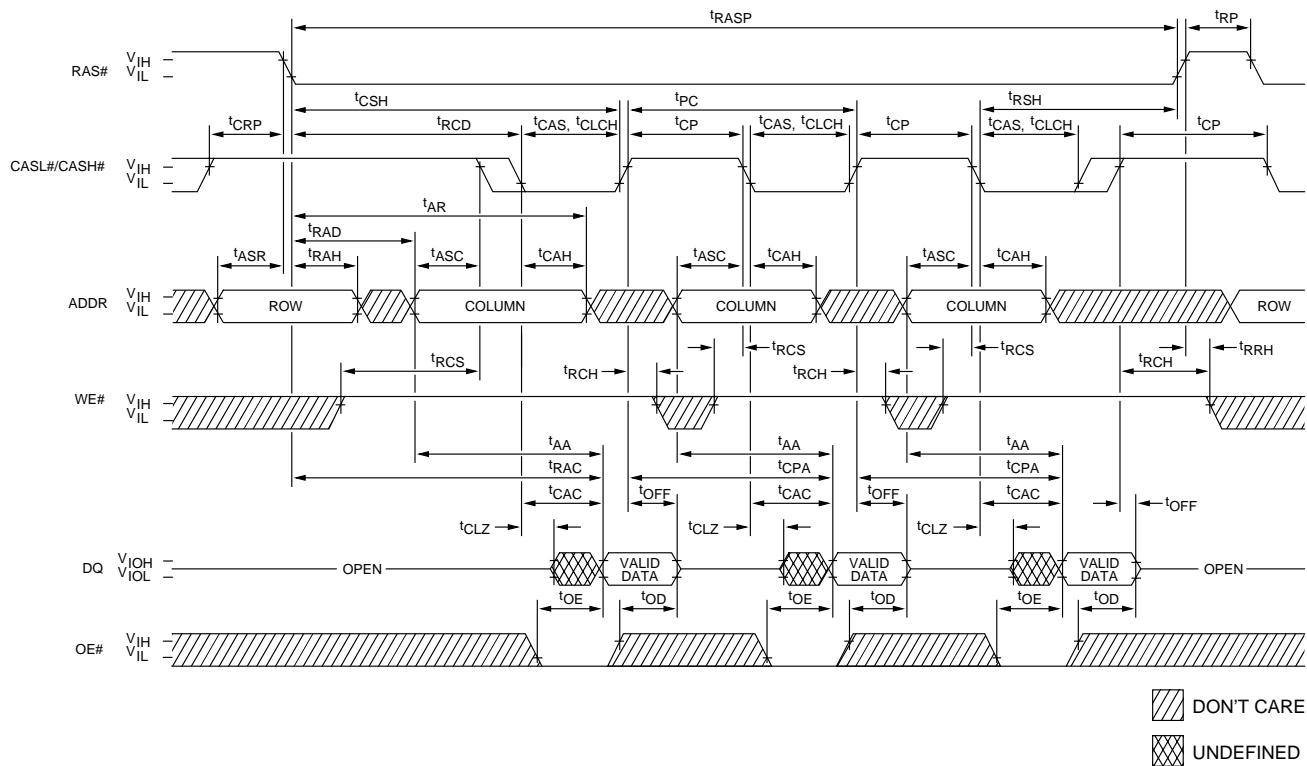


**TIMING PARAMETERS**

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>AA</sub>		30		35	ns
t <sub>AR</sub>	45		55		ns
t <sub>ASC</sub>	0		0		ns
t <sub>ASR</sub>	0		0		ns
t <sub>AWD</sub>	55		60		ns
t <sub>CAC</sub>		15		20	ns
t <sub>CAH</sub>	10		12		ns
t <sub>CAS</sub>	15	10,000	20	10,000	ns
t <sub>CLCH</sub>	10		10		ns
t <sub>CLZ</sub>	3		3		ns
t <sub>CRP</sub>	5		5		ns
t <sub>CSH</sub>	60		70		ns
t <sub>CWD</sub>	40		45		ns
t <sub>CWL</sub>	15		20		ns
t <sub>DH</sub>	10		12		ns
t <sub>DS</sub>	0		0		ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>OD</sub>	3	15	3	20	ns
t <sub>OE</sub>		15		20	ns
t <sub>OEH</sub>	15		20		ns
t <sub>RAC</sub>		60		70	ns
t <sub>RAD</sub>	15		15		ns
t <sub>RAH</sub>	10		10		ns
t <sub>RAS</sub>	60	10,000	70	10,000	ns
t <sub>RCD</sub>	20		20		ns
t <sub>RCS</sub>	0		0		ns
t <sub>RP</sub>	40		50		ns
t <sub>RSH</sub>	15		20		ns
t <sub>RWC</sub>	155		180		ns
t <sub>RWD</sub>	85		95		ns
t <sub>RWL</sub>	15		20		ns
t <sub>WP</sub>	10		15		ns

### FAST-PAGE-MODE READ CYCLE

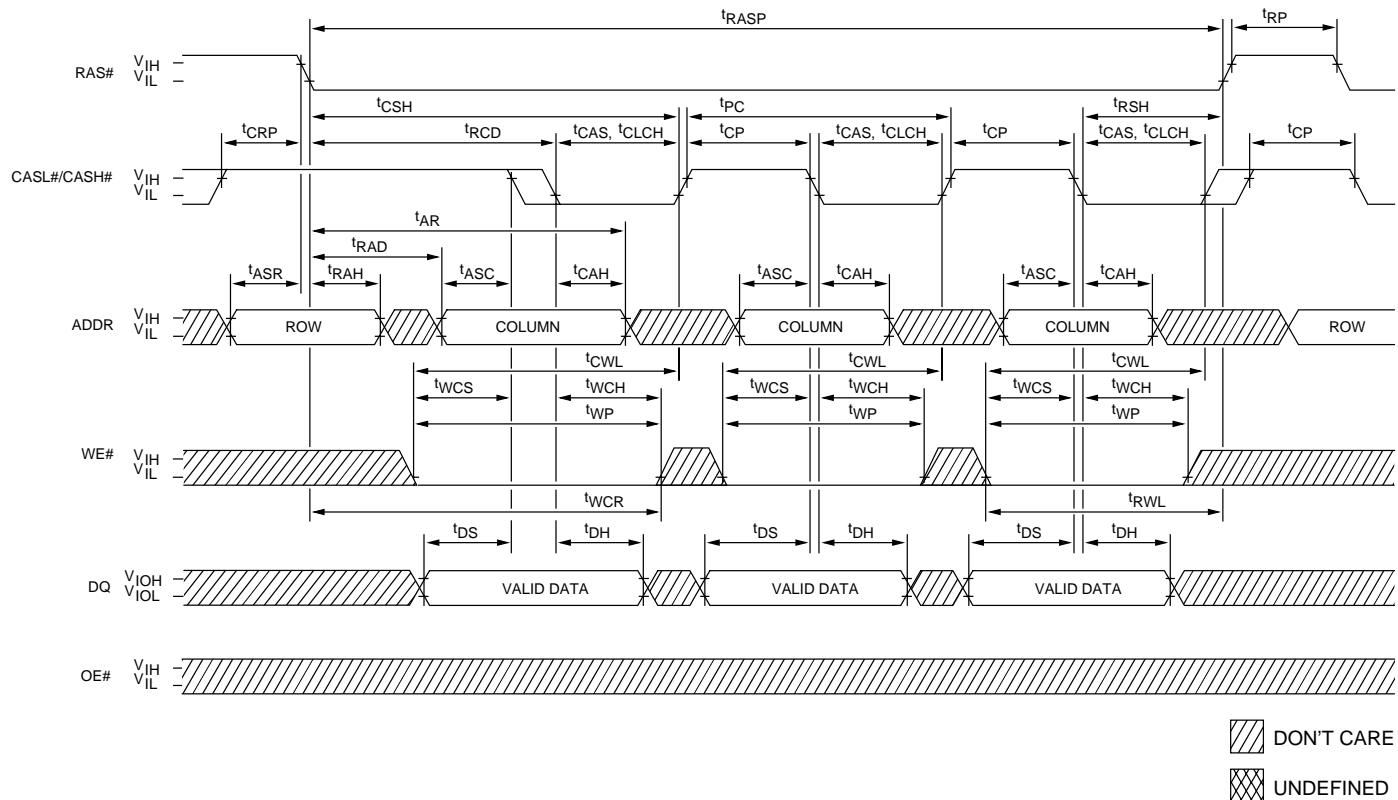


### TIMING PARAMETERS

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>AA</sub>		30		35	ns
t <sub>AR</sub>	45		55		ns
t <sub>ASC</sub>	0		0		ns
t <sub>ASR</sub>	0		0		ns
t <sub>CAC</sub>		15		20	ns
t <sub>CAH</sub>	10		12		ns
t <sub>CAS</sub>	15	10,000	20	10,000	ns
t <sub>CLCH</sub>	10		10		ns
t <sub>CLZ</sub>	3		3		ns
t <sub>CP</sub>	10		10		ns
t <sub>CPA</sub>		35		40	ns
t <sub>CRP</sub>	5		5		ns
t <sub>CSH</sub>	60		70		ns
t <sub>OD</sub>	3	15	3	20	ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>OE</sub>				15	ns
t <sub>OFF</sub>	3		15	3	ns
t <sub>PC</sub>	35			40	ns
t <sub>RAC</sub>				60	ns
t <sub>RAD</sub>	15			15	ns
t <sub>RAH</sub>	10			10	ns
t <sub>RASP</sub>	60		125,000	70	ns
t <sub>RCD</sub>	20			20	ns
t <sub>RCH</sub>	0			0	ns
t <sub>RCS</sub>	0			0	ns
t <sub>RP</sub>	40			50	ns
t <sub>RRH</sub>	0			0	ns
t <sub>RSH</sub>	15			20	ns

### FAST-PAGE-MODE EARLY-WRITE CYCLE



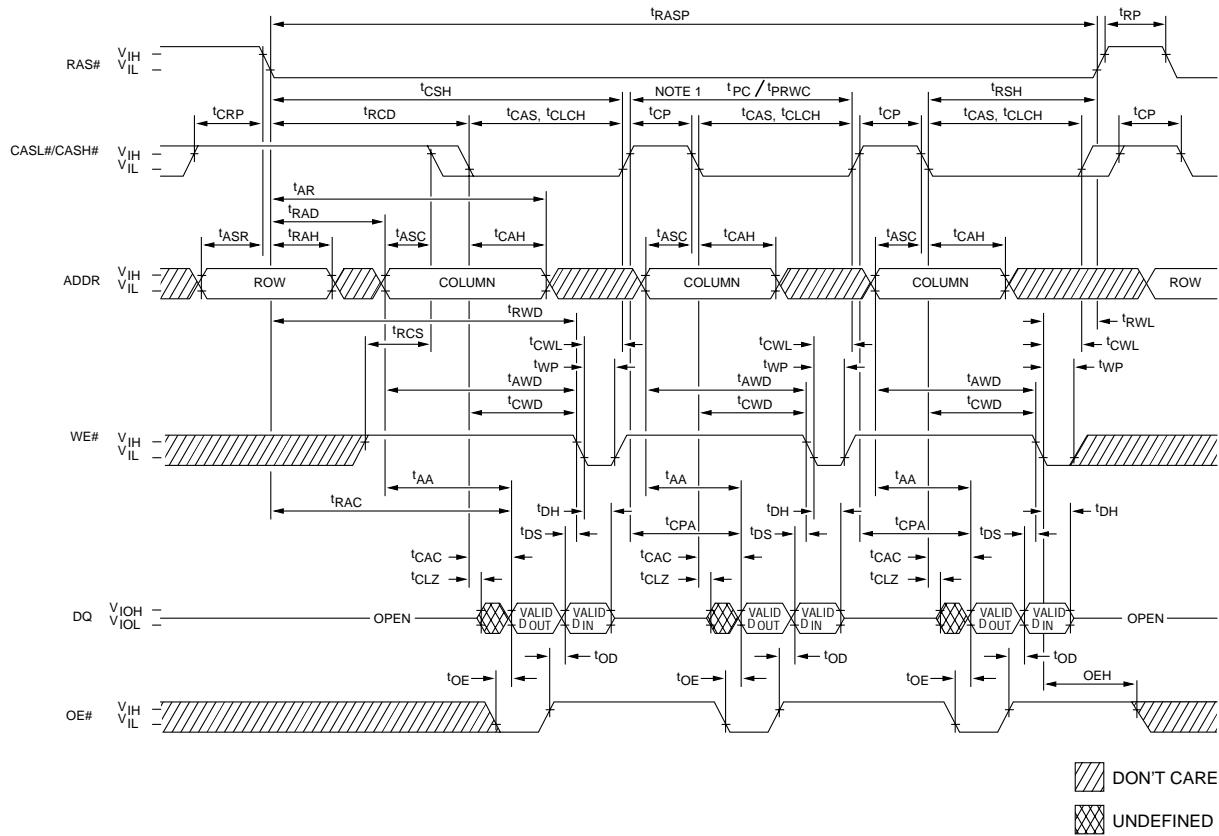
### TIMING PARAMETERS

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
tAR	45		55		ns
tASC	0		0		ns
tASR	0		0		ns
tCAH	10		12		ns
tCAS	15	10,000	20	10,000	ns
tCLCH	10		10		ns
tCP	10		10		ns
tCRP	5		5		ns
tCSH	60		70		ns
tCWL	15		20		ns
tDH	10		12		ns
tDS	0		0		ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
tPC	35		40		ns
tRAD	15		15		ns
tRAH	10		10		ns
tRASP	60	125,000	70	125,000	ns
tRCD	20		20		ns
tRP	40		50		ns
tRSH	15		20		ns
tRWL	15		20		ns
tWCH	10		12		ns
tWCR	45		55		ns
tWCS	0		0		ns
tWP	10		15		ns

## **FAST-PAGE-MODE READ-WRITE CYCLE**

(LATE WRITE and READ-MODIFY-WRITE cycles)



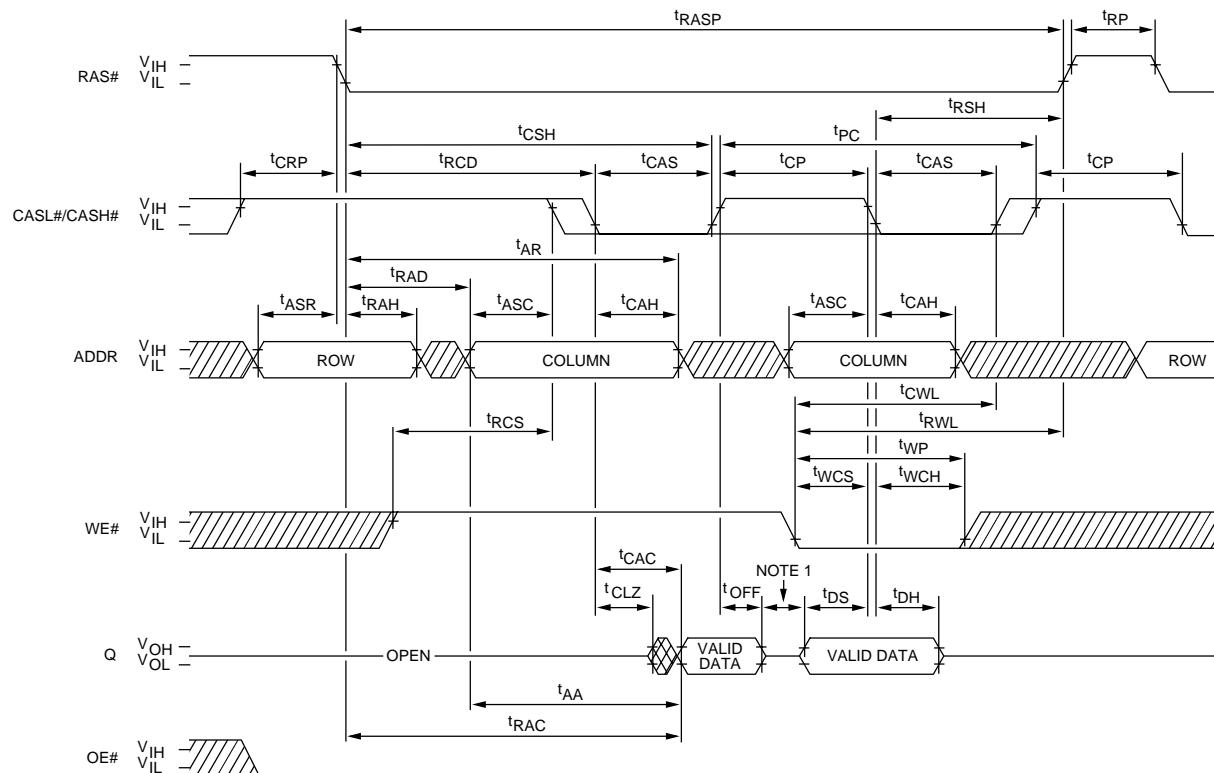
## **TIMING PARAMETERS**

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
tAA		30		35	ns
tAR	45		55		ns
tASC	0		0		ns
tASR	0		0		ns
tAWD	55		60		ns
tCAC		15		20	ns
tCAH	10		12		ns
tCAS	15	10,000	20	10,000	ns
tCLCH	10		10		ns
tCLZ	3		3		ns
tCP	10		10		ns
tCPA		35		40	ns
tCRP	5		5		ns
tCSH	60		70		ns
tCWD	40		45		ns
tCWL	15		20		ns
tDH	10		12		ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
tDS	0		0		ns
tOD	3	15	3	20	ns
tOE		15		20	ns
tOEH	15		20		ns
tPC	35		40		ns
tPRWC	85		95		ns
tRAC		60		70	ns
tRAD	15		15		ns
tRAH	10		10		ns
tRASP	60	125,000	70	125,000	ns
tRCD	20		20		ns
tRCS	0		0		ns
tRP	40		50		ns
tRSH	15		20		ns
tRWD	85		95		ns
tRWL	15		20		ns
tWP	10		15		ns

**NOTE:** 1.  $t_{PC}$  is for LATE WRITE only.

**FAST-PAGE-MODE READ-EARLY-WRITE CYCLE  
(Pseudo READ-MODIFY-WRITE)**



DON'T CARE

UNDEFINED

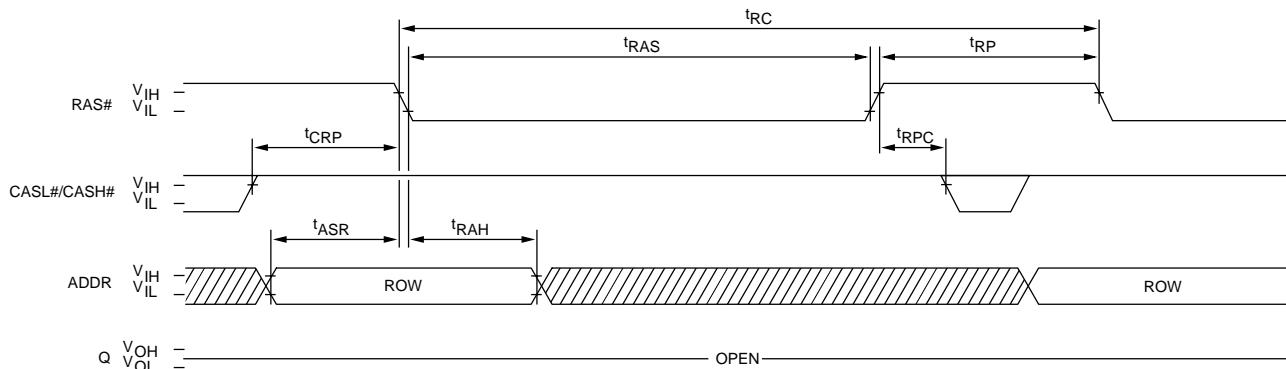
**TIMING PARAMETERS**

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>AA</sub>		30		35	ns
t <sub>AR</sub>	45		55		ns
t <sub>ASC</sub>	0		0		ns
t <sub>ASR</sub>	0		0		ns
t <sub>CAC</sub>		15		20	ns
t <sub>CAH</sub>	10		12		ns
t <sub>CAS</sub>	15	10,000	20	10,000	ns
t <sub>CLZ</sub>	3		3		ns
t <sub>CP</sub>	10		10		ns
t <sub>CRP</sub>	5		5		ns
t <sub>CSH</sub>	60		70		ns
t <sub>CWL</sub>	15		20		ns
t <sub>DH</sub>	10		12		ns
t <sub>DS</sub>	0		0		ns

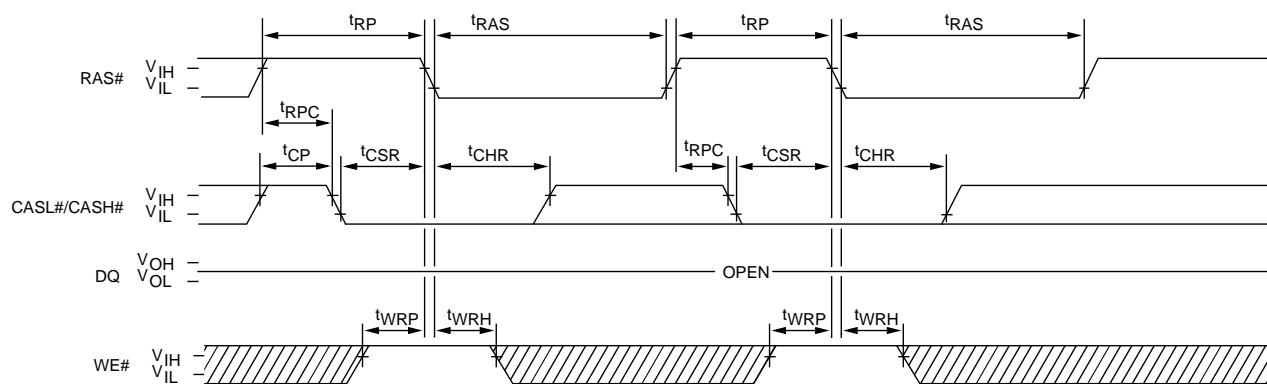
SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>OFF</sub>	3	15	3	20	ns
t <sub>PC</sub>	35		40		ns
t <sub>RAC</sub>		60		70	ns
t <sub>RAD</sub>	15		15		ns
t <sub>RAH</sub>	10		10		ns
t <sub>RASP</sub>	60	125,000	70	125,000	ns
t <sub>RCD</sub>	20		20		ns
t <sub>RCS</sub>	0		0		ns
t <sub>RP</sub>	40		50		ns
t <sub>RSH</sub>	15		20		ns
t <sub>RWL</sub>	15		20		ns
t <sub>WCH</sub>	10		12		ns
t <sub>WCS</sub>	0		0		ns
t <sub>WP</sub>	10		15		ns

**NOTE:** 1. t<sub>PC</sub> is for LATE WRITE only.

**RAS#-ONLY REFRESH CYCLE  
(OE# and WE# = DON'T CARE)**



**CBR REFRESH CYCLE  
(Addresses and OE# = DON'T CARE)**



DON'T CARE

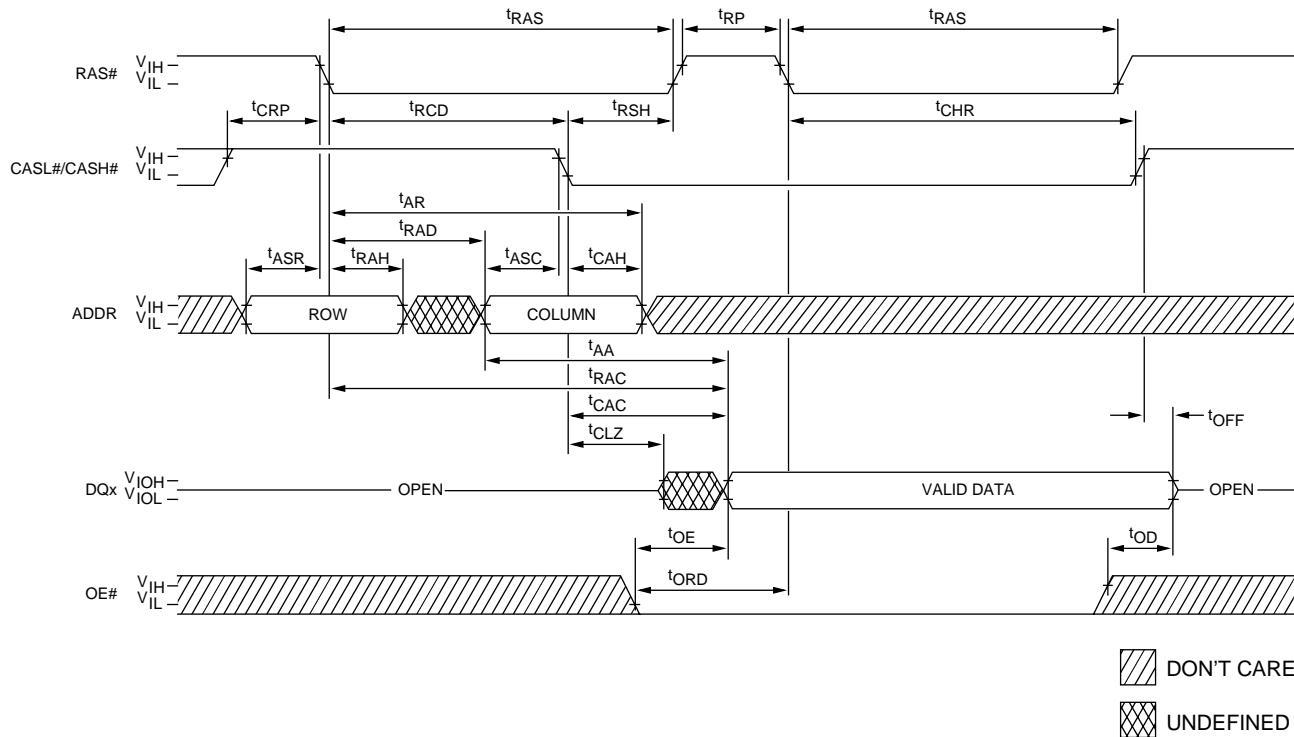
UNDEFINED

**TIMING PARAMETERS**

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>ASR</sub>	0		0		ns
t <sub>CHR</sub>	10		15		ns
t <sub>CP</sub>	10		10		ns
t <sub>CRP</sub>	5		5		ns
t <sub>CSR</sub>	5		5		ns
t <sub>RAH</sub>	10		10		ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>RAS</sub>	60	10,000	70	10,000	ns
t <sub>RC</sub>	110		130		ns
t <sub>RP</sub>	40		50		ns
t <sub>RPC</sub>	0		0		ns
t <sub>WRH</sub>	10		10		ns
t <sub>WRP</sub>	10		10		ns

**HIDDEN REFRESH CYCLE<sup>21</sup>**  
(WE# = HIGH; OE# = LOW)

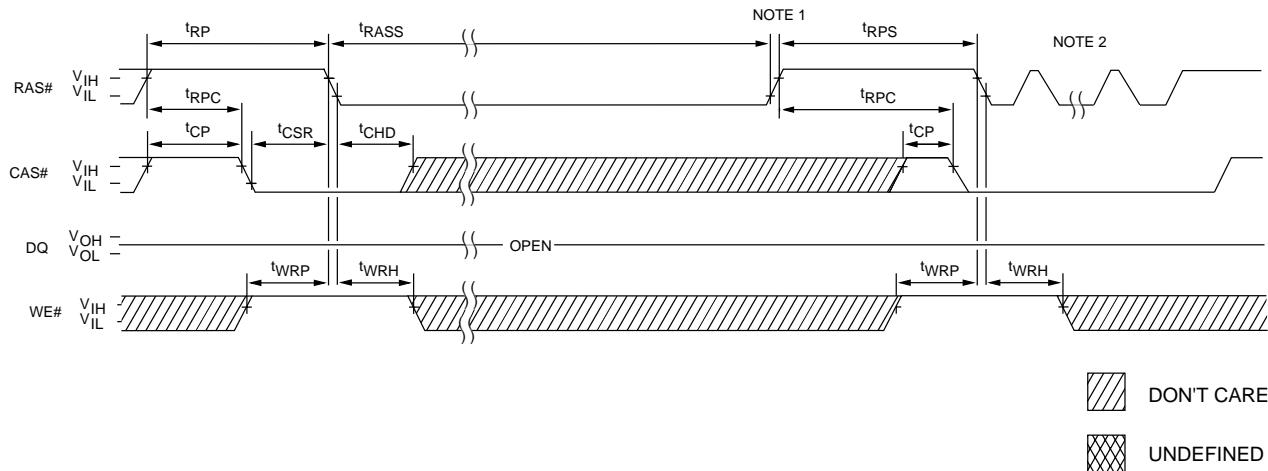


**TIMING PARAMETERS**

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>AA</sub>		30		35	ns
t <sub>AR</sub>	45		55		ns
t <sub>ASC</sub>	0		0		ns
t <sub>ASR</sub>	0		0		ns
t <sub>CAC</sub>		15		20	ns
t <sub>CAH</sub>	10		12		ns
t <sub>CHR</sub>	10		15		ns
t <sub>CLZ</sub>	3		3		ns
t <sub>CRP</sub>	5		5		ns
t <sub>OD</sub>	3	15	3	20	ns

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
t <sub>OE</sub>		15		20	ns
t <sub>OFF</sub>	3	15	3	20	ns
t <sub>ORD</sub>	0		0		ns
t <sub>RAC</sub>		60		70	ns
t <sub>RAD</sub>	15		15		ns
t <sub>RAH</sub>	10		10		ns
t <sub>RAS</sub>	60	10,000	70	10,000	ns
t <sub>RCD</sub>	20		20		ns
t <sub>RP</sub>	40		50		ns
t <sub>RSH</sub>	15		20		ns

**SELF REFRESH CYCLE**  
(Addresses and OE# = DON'T CARE)



**TIMING PARAMETERS**

SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
$t_{CHD}$	15		15		ns
$t_{CLCH}$	10		10		ns
$t_{CP}$	10		10		ns
$t_{CSR}$	5		5		ns
$t_{RASS}$	100		100		$\mu s$

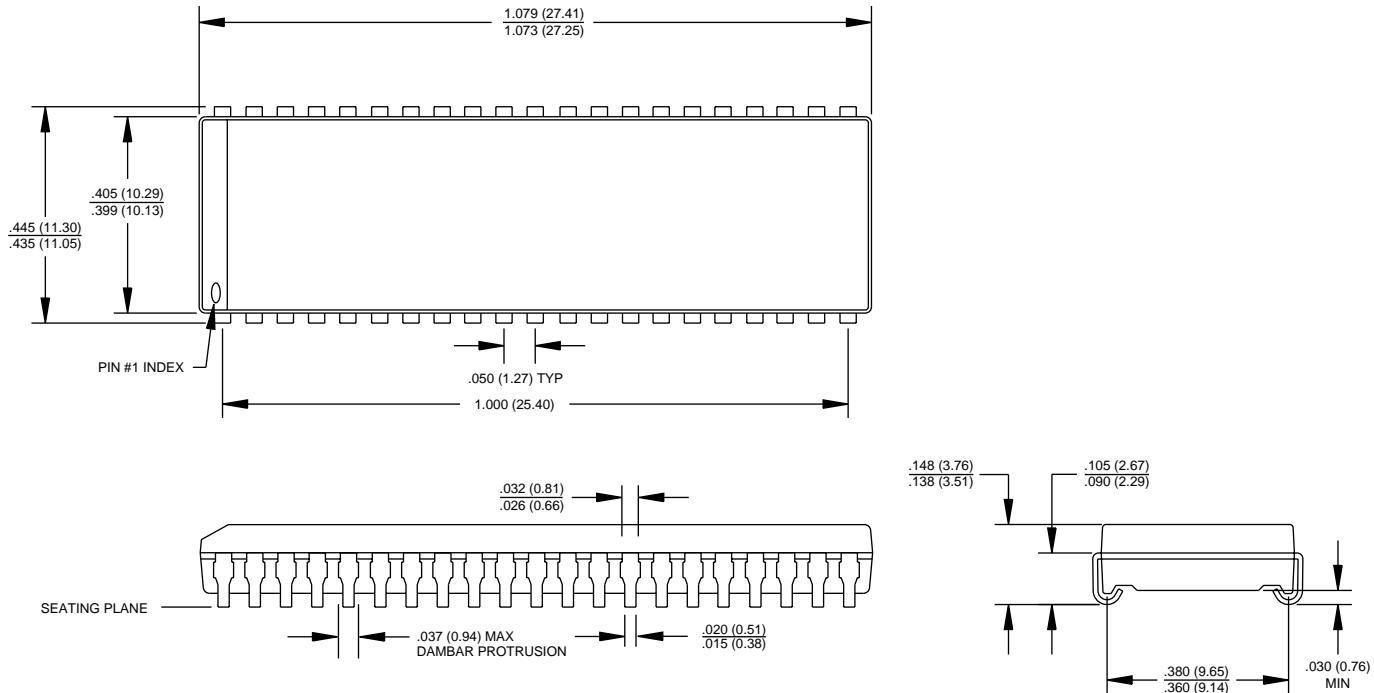
SYMBOL	-6		-7		UNITS
	MIN	MAX	MIN	MAX	
$t_{RP}$	40		50		ns
$t_{RPC}$	0		0		ns
$t_{RPS}$	110		130		ns
$t_{WRH}$	10		10		ns
$t_{WRP}$	10		10		ns

**NOTE:**

- Once  $t_{RASS}$  (MIN) is met and RAS# remains LOW, the DRAM will enter Self Refresh mode.
- Once  $t_{RPS}$  is satisfied, a complete burst of all rows should be executed.

**42-PIN PLASTIC SOJ (400 mil)**

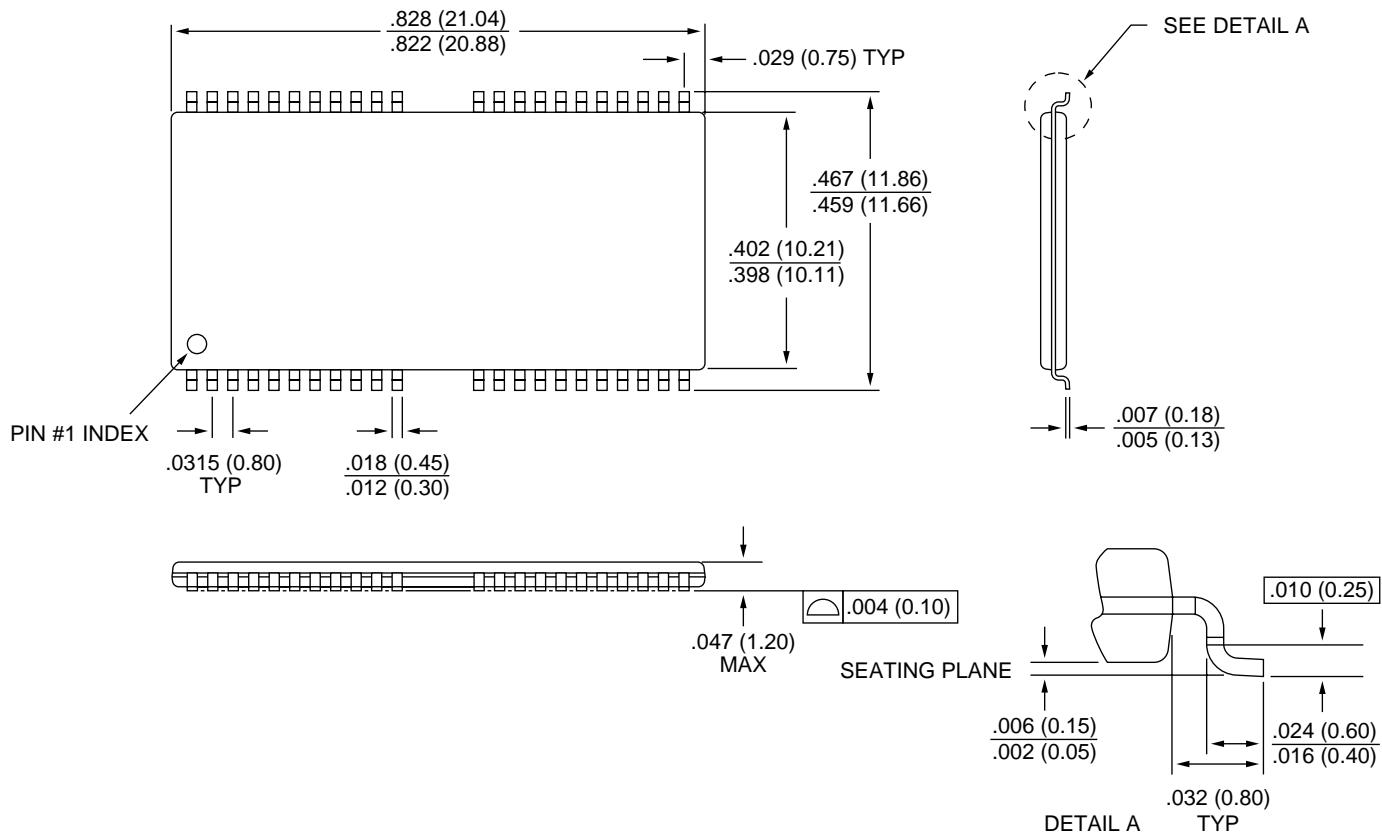
**DA-7**



**NOTE:** 1. All dimensions in inches (millimeters)  $\frac{\text{MAX}}{\text{MIN}}$  or typical where noted.  
 2. Package width and length do not include mold protrusion; allowable mold protrusion is .01" per side.

**44/50-PIN PLASTIC TSOP (400 mil)**

**DB-6**



**NOTE:** 1. All dimensions in inches (millimeters)  $\frac{\text{MAX}}{\text{MIN}}$  or typical where noted.  
 2. Package width and length do not include mold protrusion; allowable mold protrusion is .01" per side.

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